## <u>Onsemí</u>

## DFNW5 5x6, FULL-CUT SO8FL WF CASE 507BD ISSUE O DATE 13 APR 2021 - A NDTES Т TES: DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009. CONTROLLING DIMENSION: MILLIMETERS DIMENSIONS DI AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. THIS PACKAGE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING. B 1. 2. 3. D1 4. PIN 1 MILLIMETERS IDENTIFIER F1 DIM MIN. NDM. MAX. Δ 0.90 1.00 1.10 0.05 Α1 0.00 -4X θ b 0.33 0.41 0.51 PLATED ARE 0.23 0.28 0.33 С TOP VIEW D 5.00 5.15 5.30 A1 5.00 DETAIL A D1 4.80 5.20 Ċ // 0.10 C D2 3.90 4.10 4.30 SEATING PLANE DETAIL Α Ε 6.00 6.15 6.30 \_\_\_\_0.10 C F1 5.705.90 6.10 C SEATING 3.55 E2 3.75 3.95 SIDE VIEW 1.27 BSC е G 0.50 0.55 0.70 8X b G1 0.26 0.36 0.46 MOLD COMPOUND AT BOTTOM OF TIE BAR REMAIN 0.05 C e 1.25 1.40 k 1.10 e/2 0.50 0.70 0.60 T. DETAIL B -DETAIL B L10.150 REF 1 Δ М 3.00 3.40 3.80 ſ G1-0° \_\_\_ 12° θ 2X 0.75 F<sub>2</sub> PIN 5 (EXPOSED PAD) 0.70 ٦ L1 D2 4X BOTTOM VIEW -1.23 1.28 GENERIC **MARKING DIAGRAM\*** -075 3.29 XXXXXX RECOMMENDED AYWZZ MOUNTING FOOTPRINT For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D. \* XXXX = Specific Device Code \*This information is generic. Please refer to А = Assembly Location device data sheet for actual part marking. Y = Year Pb-Free indicator, "G" or microdot "•", may W = Work Week or may not be present. Some products may not follow the Generic Marking. ΖZ = Assembly Lot Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DOCUMENT NUMBER:** 98AON31027H DFNW5 5x6, FULL-CUT SO8FL WF **DESCRIPTION:** PAGE 1 OF 1 onsemi and OnSemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves

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